

CLAIMS

What is claimed is:

1. A method for forming an interposer substrate, comprising:
providing a substantially planar substrate;
forming an elongated interconnect slot comprising a plurality of longitudinally adjacent segments separated by at least one transversely extending crosspiece.
2. The method of claim 1, further including forming the interconnect slot by milling through the substrate and the at least one crosspiece comprises at least one unmilled portion of the substrate lying intermediate opposing ends of the interconnect slot.
3. The method of claim 2, further comprising producing filleted side edges on the crosspiece during the milling.
4. The method of claim 1, wherein forming an elongated interconnect slot comprises forming a unitary elongated interconnect slot and forming the crosspiece by bonding a segment of material transversely across the interconnect slot at a location intermediate opposing ends thereof.
5. The method of claim 4, wherein forming the crosspiece comprises forming a tape segment coated with an adhesive on opposing sides thereof and adhering the tape segment to a surface of the substantially planar substrate.

6. The method of claim 1, wherein forming an elongated interconnect slot comprises forming a unitary elongated interconnect slot, forming an "I"-shaped segment of material and bonding a head portion of the "I"-shaped segment to the substrate on one side of the interconnect slot and a foot portion of the "I"-shaped segment to the substrate on an opposing side of the interconnect slot with a body portion of the "I"-shaped segment extending transversely thereacross to form the crosspiece.

7. The method of claim 6, further comprising forming the "I"-shaped segment as a film having an adhesive coating on opposing sides thereof.

8. The method of claim 6, further comprising forming the "I"-shaped segment as a substantially rigid plastic segment.

9. The method of claim 1, wherein forming an elongated interconnect slot comprises forming a unitary elongated interconnect slot, forming a "T"-shaped element having a body and a cap, extending the body into the interconnect slot in contact with opposing sides thereof and bonding legs of the cap extending transversely to the interconnect slot over a surface of the substrate thereto to form the crosspiece.

10. The method of claim 1, wherein forming an elongated interconnect slot comprises forming a unitary elongated interconnect slot, forming a tape segment of a polymeric material containing a reinforcement material, disposing the tape segment transversely across the interconnect slot and bonding the tape segment to a surface of the substrate.

11. The method of claim 1, wherein forming an elongated interconnect slot comprises forming a unitary elongated interconnect slot, interposing a bar of material transversely between opposing sides of the interconnect slot and bonding the bar thereto.

12. The method of claim 1, further including forming the elongated interconnect slot to a length of about 67% or more of a length of the substrate.

13. The method of claim 12, further including forming the elongated interconnect slot to a length of about 70 to 80% of a length of the substrate.

14. The method of claim 1, further including locating the crosspiece substantially at a longitudinal midpoint of the interconnect slot.